

27MAR2012 Rev. A

SIM CONNECTOR PUSH-PUSH SUPER LOWPROFILE TYPE

1.Introduction:

1.1 Objective

Testing was performed on the SIM CONNECTOR PUSH-PUSH SUPER LOWPROFILE TYPE to determine if it meets the requirement of product specifications, 108-78899

1.2 Scope

This report covers the electrical, mechanical and environment performance requirements of the SIM CONNECTOR PUSH-PUSH SUPER LOWPROFILE TYPE.

The qualification testing was performed between 19 AUG 2011 and 27 SEP 2011.

The following documents form a part of this specification to the extent specified herein. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

1.3 Conclusion

SIM CONNECTOR PUSH-PUSH SUPER LOWPROFILE TYPE meets the electorical, mechanical and environmental performance requirements of product specifications, 108-78899

1.4 Product description

SIM CONNECTOR PUSH-PUSH SUPER LOWPROFILE TYPE is designed to make a connection between a Subscriber Identity Module (SIM) and printed circuit board.

1.5 Test samples

Samples were taken randomly from current production. The follwing samples were used.

Part number	Description
2174918-1	SIM CONNECTOR PUSH-PUSH SUPER LOWPROFILE TYPE
-	Test card for mechanical Gemplus : GEN31-30 GX3GV3-0-256K
-	Test card for contact resistance TB-1524

Fig.1

* Trademark



2. Test contents

Para.	Test items	Requirements	Judgment
2.1	Examination of product	Visual inspection No physical damage	Acceptable
		Electrical requirements	
2.2	Contact resistance (low level)	 Initial contact resistance: 100 mΩ Max. Max contact resistance after group testing: 100 mΩ Max. Contact resistance includes also the bulk resistance due to terminal After any environmental test for every contact Detection switch: 300mΩ Max. Mate connector with dry circuit (20mV, 100mA Max.) at min, deflection position 4-wire measurement required Measure resistance with minimum thickness memory card (or PWB) (IEC 60512-2-1) 	Acceptable
2.3	Insulation resistance	· 1000MΩ Min. ·Unmated connector with 500 VDC between adjacent contact for 1 minute (IEC 60512-3-1)	Acceptable
2.4	Dielectric strength	No voltage breakdown Unmated connector with 500 VAC between adjacent contact for 1 minute (IEC 60512-3-1)	Acceptable
2.5	Temperature rise	·30°C Max. under loaded rating current (0.5A) ·Contacts series-,apply test current of loaded rating current of the circuit ·Measure the temperature rising by probing on soldered areas of contacts ·After the temperature becomes stabilized deduct ambient temperature from the measured	Acceptable

Fig. 2 (Cont.)

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Para.	Test items	Requirements	Judgment
		Mechanical requirements	
2.6	Peeling strength	-25N MinNo loosening from PWB -No mechanical damage -Every axis directions -Load is applied to the whole side of the connector on PWB Left OOO OOO Down	Acceptable
2.7	Card locking force	·2 N Max. (before and after 3000 mating/unmating cycle with virgin card) ·Card should not drop out during normal operation and normal handling ·Not to fly out during card removal	Acceptable
2.8	Durability (3000 cycles)	Contact resistance: 100 mΩ Max. at minimum deflection case No mechanical damage for connector as well as SIM cards Eject length: 2.8mm Ref. Mating contacts at 4-10 cycles/minute, including pause between mate/unmate to 3000 cycles After every 10 (max.) cycles blow with dry air	Acceptable
2.9	Wrongly Insertion test card upside down	·25N Min. ·No mechanical damage ·The card cannot be stuck in the reader	Acceptable
2.10	Retention force of contact	Solderable terminal 0.8N Min. Per contact Pulling out a contact on the solder tail, away from the housing	Acceptable

Fig. 2 (Cont.)

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Para.	Test items	Requirements	Judgment
ı aıa.	Tool Romo	Environmental requirements	Gaaginene
2.11	Dry cold (steady state)	 No mechanical damage No change to performance Contact resistance: 100mΩ Max.(Data) - 40°C for 96hours; recovery period 1-2hours under ambient atmospheric conditions (IEC60068-2-1Ab) 	Acceptable
2.12	Dry heat (steady state)	No mechanical damage No change to performance Contact resistance: 100mΩ Max.(Data) +85°C for 96 hours; recovery period 1-2hours under ambient atmospheric conditions (IEC60068-2-2Bb)	Acceptable
2.13	Thermal shock (change of temperature)	 No mechanical damage No change to performance Contact resistance: 100mΩ Max.(Data) 25 cycle at T_a = -55 °C for 0.5 hours; then change of temp=25°C Max. 5 minutes; then T_b=+85°C for 0.5 hours; then cool to ambient Recovery: 2 hours at ambient atmosphere (IEC60068-2-14 Test Na) 	Acceptable
2.14	Humidity - temperature cycling	 No change to performance Contact resistance:100 mΩ Max. Insulation resistance should be measured Measure the resistance without opening the mating after test Temp 25-65°C, RH 50-80% for 10 cycles Cold shock -10°C performed Mated tests: standby mode (power on) 1.8V,10 mA (EIA-364-31) 	Acceptable
		No corrosion on contact area after testing Unmated tests: -Connector with free contacts -No power on -Testing conditions are same	Acceptable

Fig. 2 (Cont.)

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Para.	Test items	Requirements	Judgment
2.15	SO₂ gas	 No mechanical damage No change to performance Contact resistance: 100mΩ Max. (Data) 10±3ppm, Damp 75% at 40±2°C, 48hours 	Acceptable
2.16	Vibration (random)	 Discontinuity during testing 1 µs with all contacts in series No mechanical damage No change to performance Contact resistance: 100 mΩ Max. Contact resistance for grounding: Max. 1Ω Frequency:10 - 100 Hz; 3 m²/s³ (0.0132 g²/Hz);100 - 500 Hz; -3dB/Oct. for: 3 x 60 min (X- Y- and Z-axis) (IEC60068-2-64Fh) 	Acceptable
2.17	Shock (specified pulse)	 Discontinuity during testing 1 μs with all contacts in series No mechanical damage No change to performance Contact resistance: 100 mΩ Max. Contact resistance for grounding: Max. 1Ω Pulse shape=half sine Peak acceleration =50G Duration of pulse=11ms Apply 3 shocks in each direction along the 3 mutually perpendicular axes (18 shocks) (IEC60068-2-27Ea) 	Acceptable

Fig. 2 (End)

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3. Product qualification test sequence

	Test eversination	Card thickness;						Test	group				
Para.	Test examination	minimum / maximum	1	2	3	4	5	6	7	8	9	10	11
2.1	Examination of product		1,7	1,5	1,5	1,5	1,5	1,7	1,6	1,3	1,3	1,3	1,3
2.2	Contact resistance (low level)	Min.		2,4	2,4	2,4	2,4	3,5	2,5				
2.3	Insulation resistance	Without card	2,5										
2.4	Dielectric strength	Without card	3,6										
2.5	Temperature rise	Nominal								2			
2.6	Peeling strength										2		
2.7	Card locking force	Nominal						2,6					
2.8	Durability (3000 cycles)	Maximum						4					
	Wrongly Insertion test card upside down	Nominal										2	
2.10	Retention force of contact												2
2.11	Dry cold (steady state)	Min.		3									
2.12	Dry heat (steady state)	Min.			3								
2.13	Thermal shock (change of temperature)	Min.				3							
2.14	Humidity - temperature cycling	Min.	4										
2.15	SO₂ gas	Without card/Min					3						
2.16	Vibration (random)	Min.							3				
2.17	Shock (specified pulse)	Min.							4				

⁽a) Numbers indicate sequence in which the tests are performed.

Fig. 3

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4. Test results

Test item	Unit	N	Result	Requirements	Judge -ment
			Test group 1		
Examination of product	1	5	No abnormalities	No abnormalities	Accept -able
Insulation resistance	Ω	5	86300MΩMin.	1000MΩ Min.	Accept -able
Dielectric strength	1	5	No abnormalities	No abnormalities	Accept -able
Humidity - temperature cycling	1	5	No abnormalities	No abnormalities	Accept -able
Insulation resistance	Ω	5	42700MΩMin.	1000MΩ Min.	Accept -able
Dielectric strength	-	5	No abnormalities	No abnormalities	Accept -able
Examination of product	1	5	No abnormalities	No abnormalities	Accept -able

Group 1 (End)

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Test item	ı	Unit			Resu	lt		Requirements	Judge
			Ν	Max.	Min.	Ave.	Sig.	•	-ment
				Tes	st group	2			
Examination of product			5	No abr	normaliti	es		No abnormalities	Accept -able
Contact resistance	Contact	0	30	21.71	19.79	20.65	0.60	Contact : 100mΩ Max.(Initial)	Accept
(low level)	Detection switch	mΩ	5	42.01	34.40	36.44	3.02	Detection switch : 300mΩ Max.(Initial)	-able
Contact resistance (low level)	Contact	mΩ	30	22.55	19.98	20.90	0.64	Contact : 100mΩ Max.(Final)	Accept
after dry cold (steady state)	Detection switch		5	37.13	33.06	35.10	1.61	Detection switch : 300mΩ Max.(Final)	-able
Examination of product		-	5	No abr	normaliti	es		No abnormalities	Accept -able

Test item	1	Unit			Resu	lt		Requirements	Judge
			N	Max.	Min.	Ave.	Sig.	•	-ment
				Tes	st group	3			
Examination of product		-	5	No abr	normaliti	es		No abnormalities	Accept -able
Contact resistance	Contact	mΩ	30	21.26	19.12	19.88	0.91	Contact : 100mΩ Max.(Initial)	Accept
(low level)	Detection switch	11132	5	47.06	34.07	39.95	4.87	Detection switch : 300mΩ Max.(Initial)	-able
Contact resistance (low level)	Contact	-mΩ	30	23.16	19.72	21.25	0.85	Contact : 100mΩ Max.(Final)	Accept
after dry heat (steady state)	Detection switch		5	53.14	32.61	37.68	8.52	Detection switch : 300mΩ Max.(Final)	-able
Examination of product		-	5	No abr	normaliti	es		No abnormalities	Accept -able

Group 2,3 (End)

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Test item	ı	Unit			Resu		Requirements	Judge	
			Ν	Max.	Min.	Ave.	Sig.	·	-ment
				Tes	st group	4			
Examination of product			5	No abr	normaliti	es		No abnormalities	Accept -able
Contact resistance	Contact	mΩ	30	22.47	19.87	20.94	0.64	Contact : 100mΩ Max.(Initial)	Accept
(low level)	Detection switch	11152	5	34.29	30.49	32.84	2.30	Detection switch : 300mΩ Max.(Initial)	-able
Contact resistance (low level) after thermal shock	Contact	mΩ	30	23.93	20.51	21.55	0.69	Contact : 100mΩ Max.(Final)	Accept
(change of temperature)	Detection switch	11152	5	37.74	36.23	33.31	1.73	Detection switch : 300mΩ Max.(Final)	-able
Examination of product		-	5	No abr	normaliti	es		No abnormalities	Accept -able

Test item	1	Unit			Resu			Requirements	Judge -ment
			N	Max.	Min.	Ave.	Sig.		-IIIGIII
				Tes	st group	5			
Examination of product		-	5	No abr	normaliti	es		No abnormalities	Accept -able
Contact resistance (low level)	Contact	mΩ	30	22.81	20.61	21.37	0.78	Contact : 100mΩ Max.(Initial)	Accept
	Detection switch	11152	5	35.25	32.18	33.83	1.56	Detection switch : 300mΩ Max.(Initial)	-able
Contact resistance	Contact	0	30	25.22	20.19	22.35	2.42	Contact : 100mΩ Max.(Final)	Accept
(low level) after SO ₂ gas	Detection switch	mΩ	5	38.17	33.35	35.09	1.69	Detection switch : 300mΩ Max.(Final)	-able
Examination of product		-	5	No abr	normaliti	es		No abnormalities	Accept -able

Group 4,5 (End)

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Test item	1	Unit			Resu	lt		Requirements	Judge
	•		N	Max.	Min.	Ave.	Sig.		-ment
				Tes	st group	6		Г	
Examination of product			5	No abr	ormaliti	es		No abnormalities	Accept -able
Card locking force			5	1.64	1.05	1.26	0.21	2 N Max.	Accept -able
Contact resistance (low level)	Contact	mΩ	30	21.06	19.17	20.16	0.86	Contact : 100mΩ Max.(Initial)	Accept -able
	Detection switch	11122	5	46.82	33.95	38.21	3.89	Detection switch : 300mΩ Max.(Initial)	
Durability (3000 cycles)			5	No abr	normaliti	es		No abnormalities	Accept -able
Contact resistance	Contact	mΩ	30	22.29	19.62	20.62	0.81	Contact : 100mΩ Max.(Final)	Accept
(low level) after durability (3000 cycles)	Detection switch	11122	5	33.40	31.01	32.41	1.25	Detection switch : 300mΩ Max.(Final)	-able
(3000 cycles)	Eject length	mm	5	3.440	2.930	3.198	0.203	2.8mm Ref.	Accept -able
Card locking force		N	5	1.26	1.08	1.20	0.07	2 N Max.	Accept -able
Examination of prod	uct	-	5	No abr	normaliti	es		No abnormalities	Accept -able

Group 6 (End)

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Test item		Unit	Result					Requirements	Judge
			Ν	Max.	Min.	Ave.	Sig.		-ment
Test group 7									
Examination of product		-	5	No abnormalities				No abnormalities	Accept -able
Contact resistance (low level)	Contact	mΩ	30	21.76	19.41	20.50	1.09	Contact : 100mΩ Max.(Initial) Detection switch : 300mΩ Max.(Initial)	Accept -able
	Detection switch		5	36.26	31.47	33.19	1.29		
Vibration (random)		-	5	No abnormalities				1μs Max.	Accept -able
Shock (specified pulse)		-	5	No abnormalities				1μs Max.	Accept -able
Contact resistance (low level) after vibration (random) & shock (specified pulse)	Contact	-mΩ	30	36.42	20.61	23.48	2.90	Contact : 100mΩ Max.(Final) Detection switch : 300mΩ Max. (Final)	Accept -able
	Detection switch		5	42.42	39.90	38.19	3.16		
Examination of product		-	5	No abnormalities				No abnormalities	Accept -able

Toot item	Unit	Result					Requirements	Judge	
Test item		N	Max.	Min.	Ave.	Sig.	Requirements	-ment	
Test group 8									
Examination of product	ı	5	No abnormalities				No abnormalities	Accept -able	
Temperature rise	°C	5	3.29	1.34	2.03	3.92	30°C Max.	Accept -able	
Examination of product	-	5	No abnormalities				No abnormalities	Accept -able	

Group 7,8 (End)

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Test item		Unit	N	Result	Requirements	Judge -ment				
Test group 9										
Examination of product		-	20	No abnormalities	No abnormalities	Accept -able				
Peeling strength	Left		5	223.4N	25N Min.					
	Right	N	5	156.0N	Left Right	Accept				
	Up		5	249.8N	000	-able				
	Down		5	298.2N	Down					
Examination of product		-	20	No abnormalities	No abnormalities	Accept -able				
		1								
Test item		Unit	N	Result	Requirements	Judge -ment				
				Test group 10						
Examination of product		-	5	No abnormalities	No abnormalities	Accept -able				
Wrongly insertion test card upside down		-	5	No abnormalities	No abnormalities	Accept -able				
Examination of product		-	5	No abnormalities	No abnormalities	Accept -able				
		1	1							
Test item		Unit	N	Result	Requirements	Judge -ment				
				Test group 11						
Examination of product		_	5	No abnormalities	No abnormalities	Accept -able				
Retention force of contact		N	5	13.6N Min.	1N Min.	Accept -able				
Examination of product		-	5	No abnormalities	No abnormalities	Accept -able				

Group 9,10,11 (End)

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